## BS EN IEC 60747-5-5:2020

This is a preview of "BS EN IEC 60747-5-5:...". Click here to purchase the full version from the ANSI store.



**BSI Standards Publication** 

# **Semiconductor devices**

Part 5-5: Optoelectronic devices — Photocouplers



## National foreword

This British Standard is the UK implementation of EN IEC 60747-5-5:2020. It is identical to IEC 60747-5-5:2020. It supersedes BS EN 60747-5-5:2011+A1:2015, which is withdrawn.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its committee manager.

This publication does not purport to include all the necessary provisions of a contract. Users are responsible for its correct application.

© The British Standards Institution 2020 Published by BSI Standards Limited 2020

ISBN 978 0 580 96181 6

ICS 31.080.01; 31.260

# Compliance with a British Standard cannot confer immunity from legal obligations.

This British Standard was published under the authority of the Standards Policy and Strategy Committee on 30 September 2020.

#### Amendments/corrigenda issued since publication

Date

Text affected

#### 

#### EN IEC 607/7 5 5

This is a preview of "BS EN IEC 60747-5-5:...". Click here to purchase the full version from the ANSI store.

## **EUROPÄISCHE NORM**

September 2020

ICS 31.080.01; 31.260

Supersedes EN 60747-5-5:2011 and all of its amendments and corrigenda (if any)

**English Version** 

## Semiconductor devices - Part 5-5: Optoelectronic devices -Photocouplers (IEC 60747-5-5:2020)

Dispositifs à semiconducteurs - Partie 5-5 : Dispositifs optoélectroniques - Photocoupleurs (IEC 60747-5-5:2020) Halbleiterbauelemente - Teil 5-5: Optoelektronische Bauelemente - Optokoppler (IEC 60747-5-5:2020)

This European Standard was approved by CENELEC on 2020-08-24. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Croatia, Cyprus, the Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Republic of North Macedonia, Romania, Serbia, Slovakia, Slovenia, Spain, Sweden, Switzerland, Turkey and the United Kingdom.



European Committee for Electrotechnical Standardization Comité Européen de Normalisation Electrotechnique Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

## European foreword

The text of document 47E/706/FDIS, future edition 2 of IEC 60747-5-5, prepared by SC 47E "Discrete semiconductor devices" of IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 60747-5-5:2020.

The following dates are fixed:

- latest date by which the document has to be implemented at national (dop) 2021-05-24 level by publication of an identical national standard or by endorsement
- latest date by which the national standards conflicting with the (dow) 2023-08-24 document have to be withdrawn

This document supersedes EN 60747-5-5:2011 and all of its amendments and corrigenda (if any).

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CENELEC shall not be held responsible for identifying any or all such patent rights.

## Endorsement notice

The text of the International Standard IEC 60747-5-5:2020 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60065	NOTE	Harmonized as EN 60065
IEC 60270:2000	NOTE	Harmonized as EN 60270:2001 (not modified)
IEC 60747-5-2	NOTE	Harmonized as EN 60747-5-2
IEC 60747-5-3	NOTE	Harmonized as EN 60747-5-3

(normative)

# Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: <u>www.cenelec.eu</u>.

Publication	Year	Title	<u>EN/HD</u>	Year
IEC 60068-1	2013	Environmental testing - Part 1: Genera and guidance	I EN 60068-1	2014
IEC 60068-2-1	-	Environmental testing - Part 2-1: Tests Test A: Cold	- EN 60068-2-1	-
IEC 60068-2-2	-	Environmental testing - Part 2-2: Tests Test B: Dry heat	- EN 60068-2-2	-
IEC 60068-2-6	-	Environmental testing - Part 2-6: Tests Test Fc: Vibration (sinusoidal)	- EN 60068-2-6	-
IEC 60068-2-14	-	Environmental testing - Part 2-14: Tests Test N: Change of temperature	- EN 60068-2-14	-
IEC 60068-2-17	-	Basic environmental testing procedures Part 2-17: Tests - Test Q: Sealing	- EN 60068-2-17	-
IEC 60068-2-20	-	Environmental testing - Part 2-20: Tests Test T: Test methods for solderability and resistance to soldering heat of devices with leads	d	-
IEC 60068-2-27	-	Environmental testing - Part 2-27: Tests Test Ea and guidance: Shock	- EN 60068-2-27	-
IEC 60068-2-30	-	Environmental testing - Part 2-30: Tests Test Db: Damp heat, cyclic (12 h + 12 cycle)		-
IEC 60068-2-58	-	Environmental testing - Part 2-58: Tests Test Td: Test methods for solderability resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)	ν, 1	-
IEC 60068-2-78	-	Environmental testing - Part 2-78: Tests Test Cab: Damp heat, steady state	- EN 60068-2-78	-
IEC 60112	-	Method for the determination of the proc and the comparative tracking indices of solid insulating materials		-

BS EN IEC 60747-5-5:2020

EN IEC 60747-5-5:2020 (E)

This is a preview of "BS EN IEC 60747-5-5:...". Click here to purchase the full version from the ANSI store.

IEC 60216-1	-	Electrical insulating materials - Thermal EN 60216-1 endurance properties - Part 1: Ageing procedures and evaluation of test results	-
IEC 60216-2	-	Electrical insulating materials - Thermal EN 60216-2 endurance properties - Part 2: Determination of thermal endurance properties of electrical insulating materials - Choice of test criteria	-
IEC 60664-1	2007	Insulation coordination for equipment EN 60664-1 within low-voltage systems - Part 1: Principles, requirements and tests	2007
IEC 60672-2	-	Ceramic and glass insulating materials - EN 60672-2 Part 2: Methods of test	-
IEC 60695-11-5	-	Fire hazard testing - Part 11-5: Test flames EN 60695-11-5 - Needle-flame test method - Apparatus, confirmatory test arrangement and guidance	-
IEC 61000-4-5	-	Electromagnetic compatibility (EMC) - Part EN 61000-4-5 4-5: Testing and measurement techniques - Surge immunity test	-
IEC 62368-1	2018	Audio/video, information and EN IEC 62368-1 communication technology equipment - Part 1: Safety requirements	2020

## CONTENTS

FC	OREW	DRD	5
1	Sco	ре	7
2	Norr	native references	7
3	Terr	ns and definitions	8
	3.7	Symbols for limiting values (absolute maximum system) over the operating temperature range, unless otherwise stated	16
4	Elec	trical characteristics	16
	4.1	Phototransistor output photocoupler	16
	4.2	Phototriac output photocoupler or solid state opto-relay	17
5	Pho	tocouplers providing protection against electric shock	
	5.1	General	18
	5.2	Туре	
	5.3	Ratings	
	5.3.	5	
	5.3.2	, , , , , , , , , , , , , , , , , , , ,	
	5.3.3	5	
	5.3.4	5	
	5.4 5.5	Electrical safety requirements Electrical, environmental and/or endurance test information (supplementary	18
	5.5	information)	19
	5.5.		
	5.5.2	2 Routine test	19
	5.5.3	3 Sample test	20
	5.5.4	4 Type test	20
6	Mea	suring methods for photocouplers	27
	6.1	Current transfer ratio <i>H</i> <sub>f(ctr)</sub>	27
	6.2	Input-to-output capacitance C <sub>IO</sub>	28
	6.3	Isolation resistance between input and output <i>R</i> <sub>IO</sub>	29
	6.4	Isolation test	30
	6.5	Partial discharges of photocouplers	31
	6.6	Collector-emitter saturation voltage V <sub>CE(sat)</sub> of a photocoupler	34
	6.6.	1 Collector-emitter saturation voltage (DC method)	34
	6.6.2	2 Collector-emitter saturation voltage (pulse method)	34
	6.7	Switching times <i>t</i> <sub>on,</sub> <i>t</i> <sub>off</sub> of a photocoupler	35
	6.8	Peak off-state current I <sub>DRM</sub>	37
	6.9	Peak on-state voltage V <sub>TM</sub>	39
	6.10	DC off-state current I <sub>BD</sub>	
	6.11	DC on-state voltage $V_{T}$	42
	6.12	Holding current I <sub>H</sub>	42
	6.13	Critical rate of rise of off-state voltage dV/dt	43
	6.14	Trigger input current I <sub>FT</sub>	46
	6.15	Measuring methods of common mode transient immunity (CMTI) for	A –7
7	Test	photocouplers ing methods of electrical ratings for phototriac couplers	
•	7.1	Repetitive peak off-state voltage $V_{\text{DRM}}$	
	1.1	ropolitivo peak on-state voltage / DRM	

7.2 DC off-state voltage V <sub>BD</sub>	50
Annex A (normative) Input/output safety test	51
A.1 Purpose	51
A.2 Circuit diagram	51
A.3 Circuit description	
A.4 Precautions to be observed	
A.5 Measurement procedure	
A.6 Specified conditions	
Bibliography	
Figure 1 – Time intervals for method a)	12
Figure 2 – Time intervals for method b)	
Figure 3 – Test voltage	
Figure 4 – Measurement circuit	27
Figure 5 – Measurement circuit for input to output capacitance	
- Figure 6 – Measurement circuit for isolation resistance	
- Figure 7 – Test circuit for withstanding isolation voltage	
-igure 8 – Partial discharge test circuit	
-igure 9 – Complete test arrangement connections for calibration	
-igure 10 – DC measurement circuit	
-igure 11 – Pulse measurement circuit	
- -igure 12 – Switching time measurement circuit	
Figure 13 – Switching times	
-igure 14 – Measurement circuit for peak off-state current	
Figure 15 – Waveforms of the peak off-state voltage and current	
Figure 16 – Measurement circuit for peak on-state voltage	
Figure 17 – Waveforms of the peak on-state voltage and current	
Figure 18 – Measurement circuit for DC off-state current	
Figure 19 – Measurement circuit for DC on-state voltage	
Figure 20 – Measurement circuit for holding current	
Figure 21 – Measurement circuit for critical rate of rise of off-state voltage	
Figure 22 – Exponential waveform of the off-voltage ( $V_{\rm D}$ )	
Figure 23 – Linear pulse form of the off-voltage ( $V_D$ )	
Figure 24 – Measurement circuit for the trigger input current	
Figure 25 – Output terminal voltage versus input forward current	
	40
Figure 26 – Common mode transient immunity (CMTI) measurement circuit for photocoupler	47
Figure 27 – Typical waveforms of the common mode pulse ( <i>V</i> <sub>CM</sub> ) and photocoupler putput ( <i>V</i> <sub>O</sub> )	49
Figure A.1 – Circuit diagram	51
Table 1 Destatransister electrical characteristics	46
Table 1 – Phototransistor electrical characteristics   Table 2 – Phototring electrical characteristics	
Table 2 – Phototriac electrical characteristics   Table 2 – Data base to base t	
able 3 – Datasheet characteristics	

Table 4 – Tests and test sequence for photocoupler providing protection against	
electrical shock	26
Table 5 – Test conditions	27
Table 6 – Specified conditions for methods a) and b)	33

## INTERNATIONAL ELECTROTECHNICAL COMMISSION

## SEMICONDUCTOR DEVICES -

## Part 5-5: Optoelectronic devices – Photocouplers

## FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC itself does not provide any attestation of conformity. Independent certification bodies provide conformity assessment services and, in some areas, access to IEC marks of conformity. IEC is not responsible for any services carried out by independent certification bodies.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 60747-5-5 has been prepared by subcommittee 47E: Discrete semiconductor devices, of IEC technical committee 47: Semiconductor devices.

This second edition cancels and replaces the first edition published in 2007 and Amendment 1:2013. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) optional data sheet basic insulation rating in accordance with IEC 60664-1:2007, 6.1.3.5;
- b) editorial corrections on the use of  $V_{\text{IORM}}$ ;
- c) editorial corrections on Figure 2: Time intervals for method b);
- d) addition of an alternative surge pulse  $V_{\text{IOSM}}$  test method.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
47E/706/FDIS	47E/714/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 60747 series, published under the general title *Semiconductor devices*, can be found on the IEC website.

Future standards in this series will carry the new general title as cited above. Titles of existing standards in this series will be updated at the time of the next edition.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

## SEMICONDUCTOR DEVICES -

## Part 5-5: Optoelectronic devices – Photocouplers

### 1 Scope

This part of IEC 60747 specifies the terminology, essential ratings, characteristics, safety tests, as well as the measuring methods for photocouplers.

NOTE The term "optocoupler" can also be used instead of "photocoupler".

#### 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-1:2013, Environmental testing – Part 1: General and guidance

IEC 60068-2-1, Environmental testing – Part 2-1: Tests – Test A: Cold

IEC 60068-2-2, Environmental testing – Part 2-2: Tests – Test B: Dry heat

IEC 60068-2-6, Environmental testing – Part 2-6: Tests – Test Fc: Vibration (sinusoidal)

IEC 60068-2-14, Environmental testing – Part 2-14: Tests – Test N: Change of temperature

IEC 60068-2-17, Basic environmental testing procedures – Part 2-17: Tests – Test Q: Sealing

IEC 60068-2-20, Environmental testing – Part 2-20: Tests – Test T: Test methods for solderability and resistance to soldering heat of devices with leads

IEC 60068-2-27, Environmental testing – Part 2-27: Tests – Test Ea and guidance: Shock

IEC 60068-2-30, Environmental testing – Part 2-30: Tests – Test Db: Damp heat, cyclic (12 h + 12 h cycle)

IEC 60068-2-58, Environmental testing – Part 2-58: Tests – Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)

IEC 60068-2-78, Environmental testing – Part 2-78: Tests – Test Cab: Damp heat, steady state

IEC 60112, Method for the determination of the proof and the comparative tracking indices of solid insulating materials

IEC 60216-1, *Electrical insulating materials* – *Thermal endurance properties* – *Part 1: Ageing procedures and evaluation of test results*